

**QFNW16 3x3, 0.5P**  
**CASE 484AN**  
**ISSUE A**

DATE 22 AUG 2018

DIM	MILLIMETERS		
	MIN.	NDM.	
A	0.80	0.90	
A1	---	---	
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b			0.
D			
D2	1.30	1.40	
E		J	3.10
E2	1.30	1.40	1.50
e	0.50 BSC		

**GENERIC  
MARKING DIAGRAM\***

XXXXX = Specific Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year

ear4 Lot22.7(orkLot2ar)]eek6 Tc/F3 223.7-.00225 0 .00NERIC